MEB Model Code



Base model code

MEB defines an electron beam deposition system
(main deposition technology of the equipment, some tools can integrate secondary technology as sputtering deposition)

Vacuum level

HV - high vacuum
Near UHV - near ultra high vacuum
UHV - ultra high vacuum

Number

Code differentiating versions

Subversion for the defined cfg

(mainly used for S2 and S4 configurations)

I - ion source in a process chamber also used for deposition

II - ion source in the LL chamber where the LL chamber is also used for deposition

III - ion source in a separate LL chamber and where the LL chamber is not used for deposition

IV - ion source in an independent chamber

General geometry

S - defines a configuration where an evaporation chamber is located below a deposition chamber

SL - defines a configuration in which all chambers have at least a transfer flange in the same plan

Number of chambers

For **S** configuration

- **-** - 2 chambers in a top bottom cfg.
- **2** - 2 chambers in a top bottom cfg. with additional chamber
- **4** - 2 chambers in a top bottom cfg. with 2 additional chambers

For **SL** configuration

- **-** - 2 in-line chambers
- **3/4/5** - defines the total number of chambers

Please note that « deposition » concerns only the main technique of the equipment, namely by electron beam source. Any other deposition technique is not taken into account in the definition of the model code.

Note also that the Model Code does not define the sample dimension compatibility

MP Model Code

Base model code

MP defines a sputtering deposition system
(main deposition technology of the equipment, some tools can integrate secondary technology as ebeam deposition or other techniques)



Vacuum level

HV	- high vacuum
Near UHV	- near ultra high vacuum
UHV	- ultra high vacuum

Chamber diameter

Approximate value in millimeters of the main chamber

General geometry

S - defines a configuration in which all chambers have at least a transfer flange in the same plan

Number of chambers

For **S** configuration

-	- 2 in-line chambers
3/4/5	- defines the total number of chambers

Please note that « deposition » concerns only the main technique of the equipment, namely by sputtering. Any other deposition technique is not taken into account in the definition of the model code.

Note also that the Model Code does not define the sample dimension compatibility